



ProsPower

PS05N20DA

20V Dual Channel NMOSEFT

Revision : 1.0
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ProsPower Microelectronics Co., Ltd

1. General Description

The PS05N20DA uses advanced trench technology and design to provide excellent $R_{ds(on)}$ with low gate charge. This device is suitable for use in high efficiency switching applications, DC/DC conversion, CPU power delivery and Synchronous rectification. Standard Product PS05N20DA is Pb-free (meets ROHS & Sony 259 specifications). It is offered in the very popular TSSOP8 or SOP-8 package

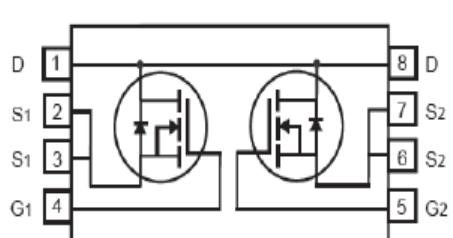
2. Applications

- Battery management
- Power management
- DC-DC converter
- Load switch
- LCD adapter

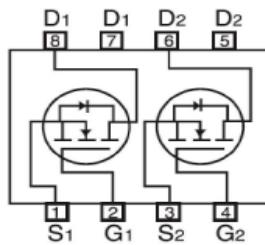
3. Features

- $V_{ds}=20V$, $I_d=5A$
- $R_{ds(on)}=<23\text{mohm}$ ($V_{gs}=4.5V$)
- Low capacitance minimizes driver loss
- Optimized gate charge minimizes switching loss

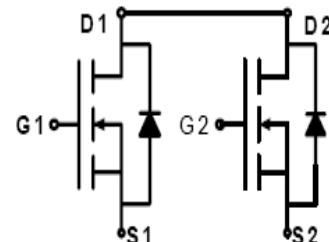
Pin Configuration



TSSOP-8



SOP-8



Schematic

Pin Descriptions

For TSSOP-8

Pin Name	Symbol	Function
Gate(4,5)	G1/G2	Device Gate terminal
Drain(1,8)	D1/D2	Device drain terminal
Source(2,3,6,7)	S1/S2	Device source terminal

For SOP-8

Pin Name	Symbol	Function
Gate(2,4)	G1/G2	Device Gate terminal
Drain(5,6,7,8)	D1/D2	Device drain terminal
Source(1,3)	S1/S2	Device source terminal

Absolute Maximum Ratings

Stress greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These stress ratings only, and functional operation of the device at these or any conditions beyond those indicated under recommended Operating Conditions is not implied. Exposure to "Absolute Maximum Rating" for extended periods may affect device reliability. Use of standard ESD handling precautions is required..

Parameter		Symbol	Maximum	Units
Drain-Source Voltage		V _{DS}	20	V
Gate-Source Voltage		V _{GS}	±12	V
Continuous Drain Current	T _C =25°C (Note 3)	I _D	5	A
Pulsed Drain Current (Note 1)		I _{DM}	30	A
Power Dissipation	T _C =25°C	P _D	1.5	W
Junction and Storage Temperature Range		T _J , T _{STG}	-65 to 150	°C

Thermal Characteristics

Parameter	Symbol	Typ.	Units
Maximum Junction-to-Ambient (Note2)	R _{θJA}	62.5	°C/W

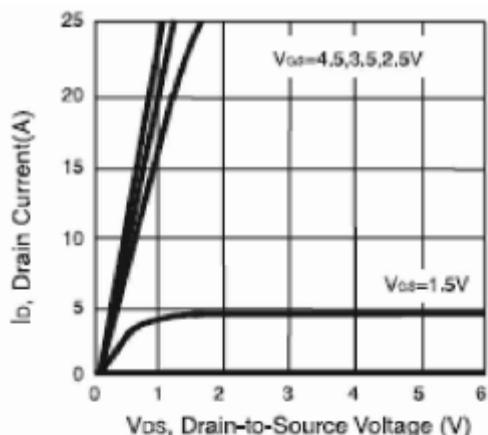
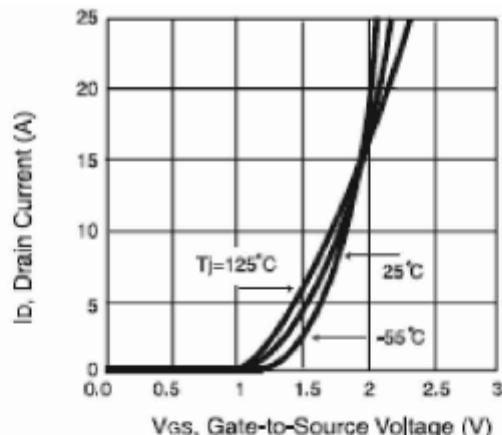
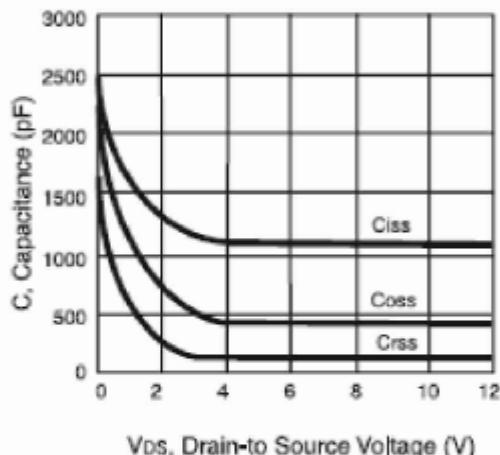
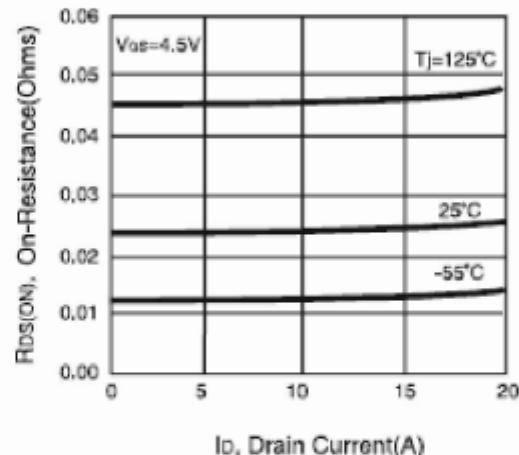
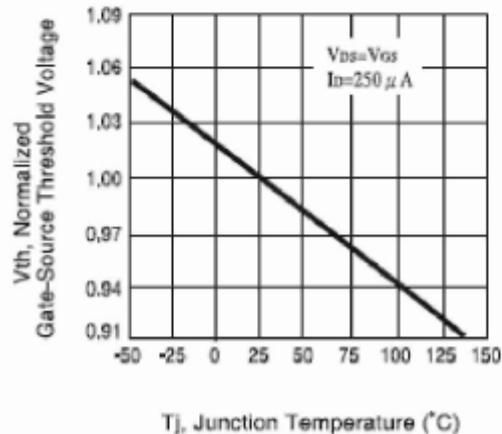
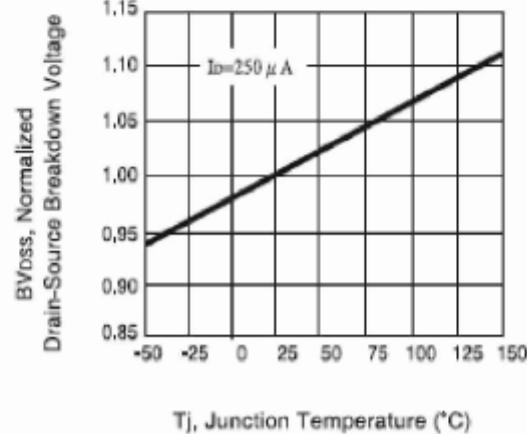
Electrical Specifications

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
STATIC PARAMETERS						
Drain-Source Breakdown Voltage	BVDss	I _D =250uA, V _{GS} =0V	20	23		V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =16V, V _{GS} =0V			1	uA
Gate-Body leakage current	I _{GSS}	V _{DS} =0V, V _{GS} =±12V			0.1	μA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	0.5	0.72	1	V
Static Drain-Source On-Resistance	R _{DS(ON)}	V _{GS} =4.5V, I _D =6A			23	mΩ
		V _{GS} =2.5V, I _D =4A			35	
Forward Transconductance	g _{FS}	V _{DS} =10V, I _D =6A	6	20		S
Diode Forward Voltage	V _{SD}	I _S =1.5A, V _{GS} =0V		0.8	1	V
DYNAMIC PARAMETERS						
Input Capacitance	C _{iss}	V _{GS} =0V, V _{DS} =8V, f=1MHz		1120	1500	pF
Output Capacitance	C _{oss}			480	630	pF
Reverse Transfer Capacitance	C _{rss}			110	160	pF
SWITCHING PARAMETERS						
Total Gate Charge	Q _g	V _{GS} =4.5V, V _{DD} =10V, I _D =6A (Note 2)		47	60	nC
Gate Source Charge	Q _{gs}			6		nC

Gate Drain Charge	Q_{gd}			8		nC
Turn-On Delay Time	$t_{D(on)}$	$I_D=1A, V_{DD}=10V,$ $V_{GEN}=4.5V, R_L=10\Omega$ $R_G=6\Omega$ (Note 2)		25	60	ns
Turn-On Rise Time	t_r			60	140	ns
Turn-Off Delay Time	$t_{D(off)}$			60	140	ns
Turn-Off Fall Time	t_f			50	60	ns

Notes

1. Pulse width limited by max. junction temperature
2. Pulse Width <= 300us, Duty Cycle <=2%
3. Surface mounted on 1 in² copper pad of FR4 board, t <= 5sec; 180°C/W when mounted on min. copper pad.

Typical Performance Characteristics

Figure 1. Output Characteristics

Figure 2. Transfer Characteristics

Figure 3. Capacitance

Figure 4. On-Resistance Variation with Drain Current and Temperature

Figure 5. Gate Threshold Variation with Temperature

Figure 6. Breakdown Voltage Variation with Temperature

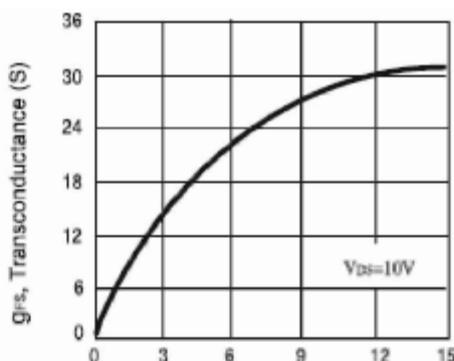
Typical Performance Characteristics (contd.)


Figure 7. Transconductance Variation with Drain Current

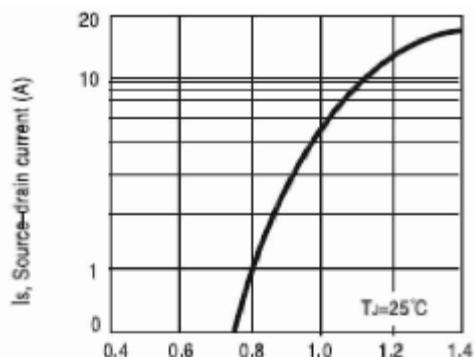


Figure 8. Body Diode Forward Voltage Variation with Source Current

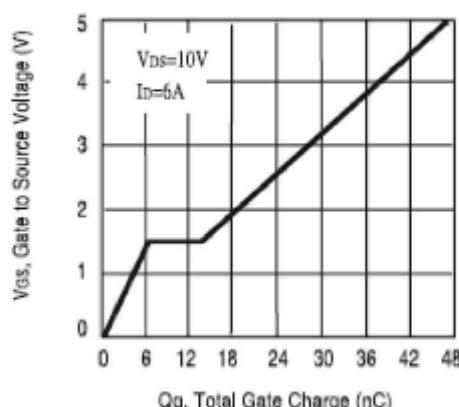


Figure 9. Gate Charge

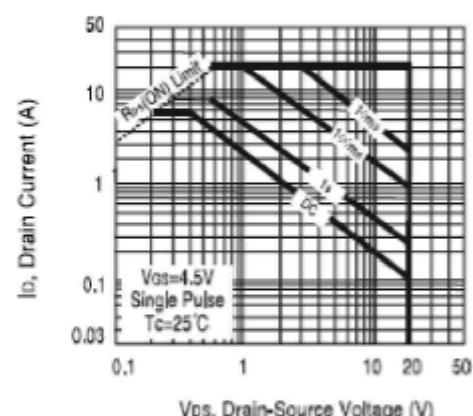


Figure 10. Maximum Safe Operating Area

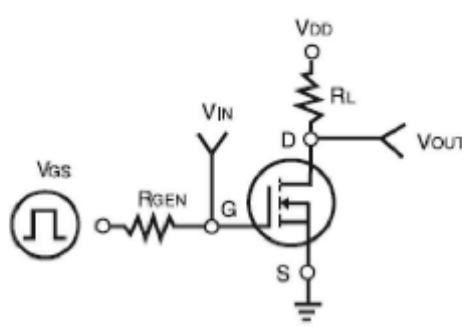


Figure 11. Switching Test Circuit

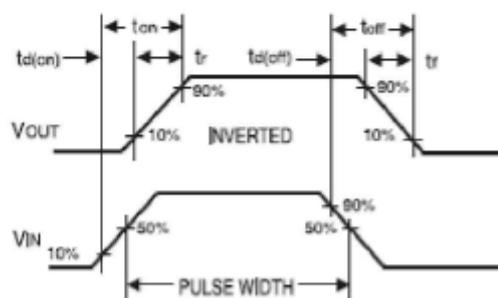
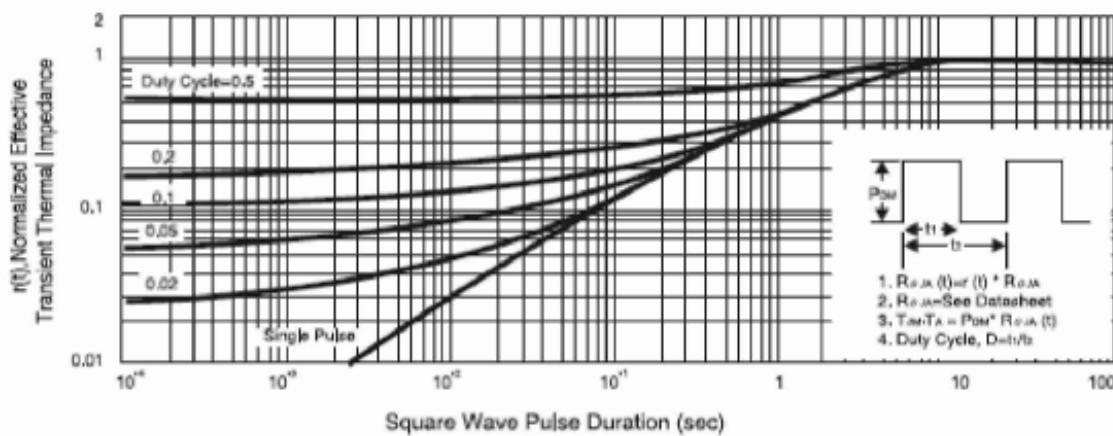
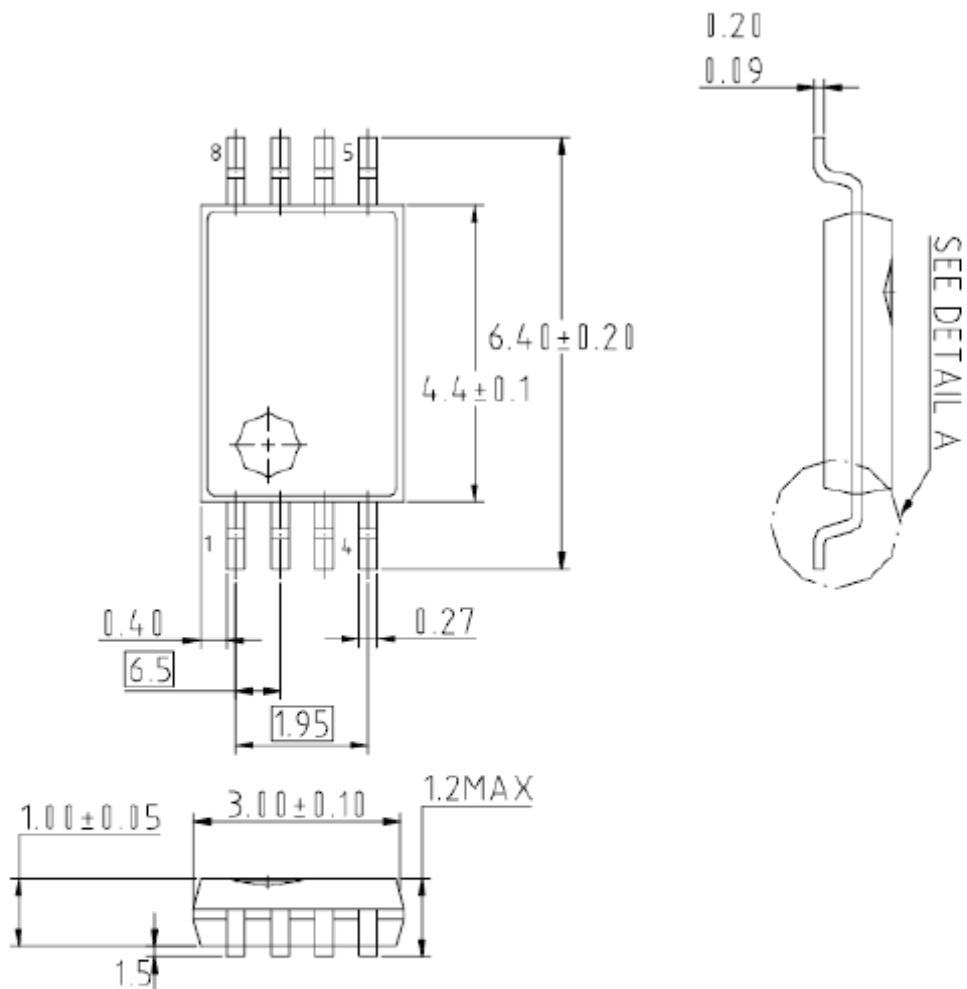


Figure 12. Switching Waveforms

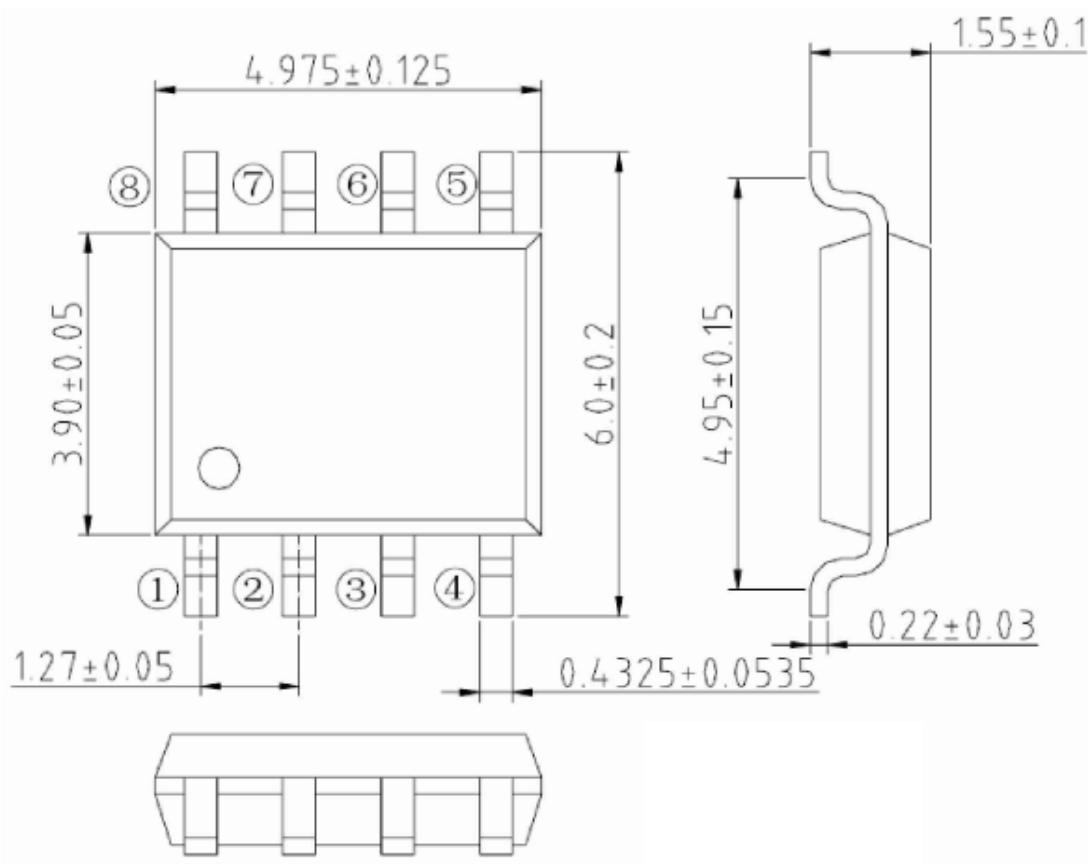
Typical Performance Characteristics (contd.)

Figure 13. Normalized Thermal Transient Impedance Curve

Package Dimensions

TSSOP-8



SOP-8



Ordering Information

Device	Operating T _j	PKG Type	Wrap	Order Number
PS05N20DA	-65C° ≤150C°	TSSOP-8	T&R	PS05N20DA-T8-TL
PS05N20DA	-65C° ≤150C°	SOP-8	T&R	PS05N20DA-S8-TL

Note: Lead Free and RoHS compliant.

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